

THE DRAWINGS AND INFORMATION CONTAINED HEREIN ARE THE EXCLUSIVE PROPERTY OF AMCOR/ANAL. THE INFORMATION, DRAWINGS AND DESIGN CONCEPTS CONTAINED HEREIN ARE CONFIDENTIAL/PROPRIETARY, SHALL BE MAINTAINED IN STRICT CONFIDENCE, AND SHALL NOT BE RELEASED TO ANY THIRD PARTY WITHOUT THE EXPRESS WRITTEN PERMISSION OF AMCOR/ANAL.

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8. REFERENCE SPECIFICATIONS:
A. AWW SPEC #001-0631-2234: PACKING OPERATION PROCEDURE.

8. REFERENCE SPECIFICATIONS:
A. AIAA SPEC #001-0591-2234: PLACING OPERATION PROCEDURE.
B. AIAA SPEC #001-0510-2068: MARKING.
C. THIS DRAWING CONFORMS TO THE JEDEC REGISTERED OUTLINE MO-151/C.
VARIATION AAJ-1.

7
A1 BALL PAD CORNER I.D. FOR PLATE MOLD: TO BE MARKED BY INK.
AUTO MOLD: DIAPHR TO BE FORKED BY MOLD CAP

6 PRIMARY DATUM Z AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

5 DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM Z.

4. THE MAXIMUM ALLOWABLE NUMBER OF SOLDER BALLS IS 484.

3. THE MAXIMUM SOLDER BALL MATRIX SIZE IS 22 X 22.

2. THE BASIC SOLDER BALL GRID PITCH IS 1.00.

1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ASME Y14.5M-1994.

NOTES: UNLESS OTHERWISE SPECIFIED

3.	THE MAXIMUM SOLDER BALL MATRIX SIZE IS 22 X 22.	UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS DECIMAL XX ±0.10 XXX ±0.05 XXXX ±0.03	ANGULAR ±1°			DATE	APPROVALS	L. MACKAY	10/21/95	DATE	10/21/95	TYPE	AAW Industrial Co., LTD. Sungdong - 3rd. Street, Korea				AMONG Electronics Inc. Chandler, Arizona, USA				 amkor	
2.	THE BASIC SOLDER BALL GRID PITCH IS 100.												AAW Industrial Co., LTD. Sungdong - 3rd. Street, Korea				AMONG Electronics Inc. Chandler, Arizona, USA				 amkor	
1.	ALL DIMENSIONS AND TOLERANCES CONFORM TO ASME Y14.5M-1994.												AAW Industrial Co., LTD. Sungdong - 3rd. Street, Korea				AMONG Electronics Inc. Chandler, Arizona, USA				 amkor	
NOTES:	UNLESS OTHERWISE SPECIFIED												AAW Industrial Co., LTD. Sungdong - 3rd. Street, Korea				AMONG Electronics Inc. Chandler, Arizona, USA				 amkor	
														PACKAGE OUTLINE - PBGA, 23.0mm X 23.0mm, 1.17mm CAP. MULTILAYER, 1.00mm PITCH, LAMINATE SUBSTRATE, AAWW								
														MATERIAL		N/A						
														FINISH		N/A						
														DO NOT SCALE DRAWING								